

TriCore[™] TC2xx AURIX[™] Family 32-bit

SYSPLL Frequency Modulation AP32244

Application Note V2.1 2016-03

Microcontrollers

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Revision History

Major changes since previous revision								
Date	Version	Changed By	Change Description					
13.11.2013	1.1	Steinecke	Section 3.2.5.1: Variable name corrections					
19.05.2014	2.0	Steinecke	Updated recommended FM settings; removed calibration contents					
14.03.2016	2.1	Steinecke	Updated recommended FM settings to MAmax=1.0%					

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About this document

1 About this document

1.1 Scope and purpose

Frequency-modulated clocks are an efficient way to significantly reduce Electromagnetic Emission (EME). Unfortunately, clock modulation implies clock edge offset (accumulated jitter, time interval error) which might inhibit the correct operation of asynchronous data interfaces. The AURIXTM System-PLL (SYSPLL) solves this problem by providing a clock Frequency Modulation technique which reduces the accumulated jitter while providing the full emission reduction (as it is known), from existing spread-spectrum systems. The Modulation Amplitude is configurable by a 10-bit field. The programmed nominal Modulation Amplitude (MA_{NOM}) should not exceed 1.5% in order to not exceed the microcontrollers' operating range. Due to constraints of data interfaces, the programmed nominal Modulation Amplitude (MA_{NOM}) should be maximal 1.0%, as specified in the data sheet. MA_{NOM} = 1.0% ist the recommended value. Nevertheless, some descriptions in this Application Note are provided for values other than 1.0% for information purpose.

Document features

Chapter 2

- General hints on clock Frequency Modulation
- Modulation parameters: modulation scheme, modulation period, Modulation Amplitude

Chapter 3

- Programming the TriCore[™] AURIX[™] TC2xx SYSPLL for Frequency Modulation
- Control register settings for various Frequency Modulation configurations
- Lookup tables for different SYSPLL configurations
- Behavior of modulation-related parameters:
- Long-term accumulated jitter
- Short-term accumulated jitter (Maximum Time Interval Error MTIE)
- Electromagnetic Emission
- Mean frequency deviation

1.2 Intended audience

The information contained in this application note addresses system architects who are looking for measures to reduce EME when using AURIX[™] microcontrollers. In particular, software developers will find useful information on how to initialize and configure the AURIX[™] Frequency Modulation.



About this document

1.3 Abbreviations

Table 1

Abbreviation	Definition
BISS	IC EMC Test Specification.
	Download from: <u>http://www.zvei.org/en/association/publications/Pages/Generic-IC-EMC-</u> Test-Specification-english.aspx
Center-spread	Symmetric Frequency Modulation around a center frequency.
EMC	Electromagnetic Compatibility The ability of a system to not disturb any other systems and being not disturbed by other systems.
EME	Electromagnetic Emission RF noise generated by (synchronous) switching activity.
FM	Frequency Modulation A periodic change of a clock rate.
FMPLL	Frequency-Modulated Phase-Locked Loop An emission-reducing clock generator for ICs.
f _{CPUx}	Operating clock for the microcontroller's central processing unit x.
f _{MOD}	Modulation frequency Determines the duration of one full modulation period.
f _{osc}	Oscillator frequency Determined by the crystal connected to the microcontroller's oscillator.
f _{PLL}	SYSPLL output frequency after Kx-divider, used as input clock for the clock domain dividers.
f _{REF}	SYSPLL input frequency after P-divider; i.e. f _{osc} / P.
f _{VCO}	VCO frequency inside the SYSPLL before Kx-divider; i.e. f _{OSC} / P · N.
f _{VCO_MEAN}	Mean VCO frequency over more than one modulation cycle.
J _{ACC}	Accumulated jitter The maximum expected offset of the real clock edge over an infinite time towards the nominal (unmodulated) clock edge without noise. <i>Note:</i> 1. Accumulated jitter is abbreviated as J_{TOT} in the data sheets.
Кх	 2. It is important to distinguish between long-term and short-term accumulated jitter. K-divider (stands for K1, K2 or K3) which divides fVCO in order to generate internal system clocks.
LF	Low Frequency Audio-range frequency.
MA	Modulation Amplitude The resulting range of real VCO frequency is half frequency shift between minimum and maximum frequency; for a symmetrical center-spread modulation this is the frequency shift between the center frequency and the maximum/minimum frequency, respectively.
MA _{NOM}	Nominal Modulation Amplitude i.e. the value programmed by the user software



About this document

Abbreviation	Definition
MA _{REAL}	Real Modulation Amplitude
	i.e. the physical value resulting from the programmed MA _{NOM} value
MTIE	Maximum Time Interval Error
	The maximum expected offset of the real clock edge towards the nominal (unmodulated) clock edge without noise after a defined time interval.
N	N-divider (clock multiplier) value in the SYSPLL.
Р	P-divider for oscillator clock in the SYSPLL.
PVT	Fabrication process window (P)
	Operating supply voltage range (V)
	Operating temperature range (T)
RF	Radio Frequency
	High frequency used as radio carrier.
RGAIN	A value to be programmed which depends on the Modulation Amplitude (MA).
SYSPLL	System-PLL (Phase Locked Loop)
	Can be configured for clock Frequency Modulation; called "PLL" in the User's Manual.
T _{MOD}	Duration of one modulation period.
T _{REF}	Duration of one SYSPLL reference clock (oscillator frequency divided by P).
T _{VCO_MEAN}	Mean VCO clock period over more than one modulation cycle.
Upspread	Frequency Modulation above a nominal frequency.
VCO	Voltage-Controlled Oscillator
	Used in the SYSPLL to compensate frequency drifts of the high-frequency clock.
VDD	Core supply voltage
	Powering the digital logic of the microcontroller.
VDDP	Pad supply voltage
	Powering the I/O stages of the microcontroller.



Introduction to frequency-modulated clocks

2 Introduction to frequency-modulated clocks

2.1 Hints on clock Frequency Modulation

Frequency-modulated clocks are also known as spread spectrum clocks. They are well established in communication techniques. FM radio uses an RF carrier which is modulated by the LF audio signal. As a result, the carrier frequency moves around its nominal frequency. The Modulation Amplitude is defined by the LF signal amplitude, while the modulation frequency is identical to the LF frequency. Both parameters vary over time.

Frequency Modulation can be used to intentionally spread the carrier energy around the nominal carrier frequency. Since the overall energy stays constant, the carrier energy is distributed over a frequency band instead of staying in one discrete frequency. As a result, the peak emission caused by the carrier is reduced. Typical applications of this spread-spectrum technique are EMC-critical applications such as automotive electronic control units.

Although 20 dB emission reductions can be reached using spread-spectrum clocks, this technique is not yet very common for automotive microcontroller systems. The main reason is the danger of inhibiting real-time functions such as asynchronous data communication or timer capture sequences. To understand this danger, let us have a closer look at the determining characteristics for frequency-modulated clocks.

Similar to radio FM, a frequency-modulated microcontroller clock is controlled by its modulation frequency (f_{MOD}) and it's Modulation Amplitude (MA).

Typically, the modulation frequency should be selected to be approximately a factor of 1000 below the clock frequency. This distance is required by the FMPLL (FM Phase Locked Loop) filter in order to prevent the modulation clock from being coupled to the VCO. A typical f_{MOD} range is from 50 kHz to 200 kHz.

The MA defines the amount of frequency shift in one direction from the mean clock frequency ("carrier"). An MA value of 1% on a 100 MHz clock means a frequency variation between 99 MHz and 101 MHz.

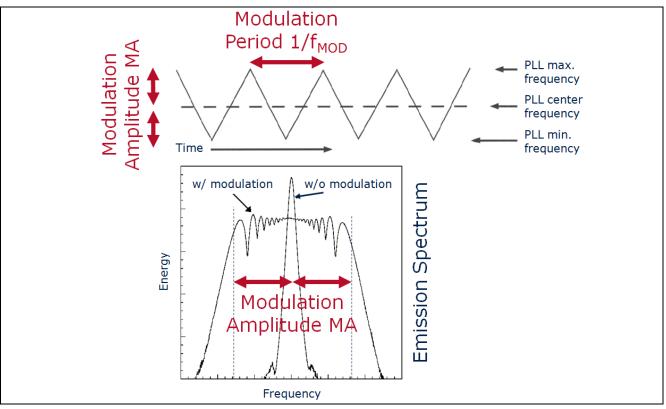


Figure 1 FMPLL function

Higher values of MA and lower values of f_{MOD} lead to less EME. Bigger MA values lead to wider sidebands where the carrier energy is distributed.



Introduction to frequency-modulated clocks

Slower f_{MOD} values lead to a smoother distribution of sideband energy; i.e. any discrete sideband frequency is activated less often.

Unfortunately, the trend of less emission together with higher MA and lower f_{MOD} is accompanied by an increasing accumulated jitter. This parameter is also known as Maximum Time Interval Error (MTIE). It means the amount of time shift between the unmodulated clock edges and the modulated clock edges over a certain time interval.

For a center-spread triangular modulation, J_{ACC-FM} is a function of the modulation frequency f_{MOD} and the Modulation Amplitude MA, according to Equation 1:

$$J_{ACC_FM}[ns] = \frac{2500 \cdot MA[\%]}{f_{MOD}[kHz]}$$

(Equation 1)

The J_{ACC-FM} value which is determined by the Frequency Modulation (FM) ranges from approximately 20 ns to well above 100 ns for typical FM settings.

In order to guarantee the reliable function of asynchronous interfaces and real-time data capture functions, the MTIE along an asynchronous frame has to stay below a certain limit defined for these interfaces. Timer modules and analog-to-digital converters may also be sensitive towards modulated clocks. This requirement for a small accumulated jitter cannot be fulfilled by a standard triangular modulation unless the Modulation Amplitude is set significantly small, resulting in insufficient emission reduction.

The following figure shows an example for $f_{PLL} = 100$ MHz, $f_{MOD} = 100$ kHz, MA = 1 %, resulting in an accumulated jitter of 25 ns.



SYSPLL Frequency Modulation AP32244

Introduction to frequency-modulated clocks

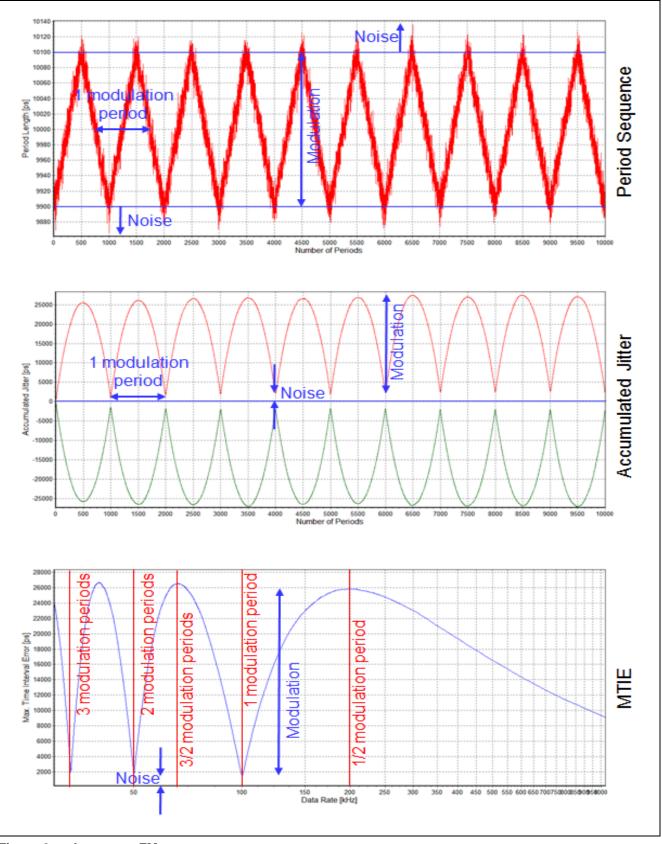


Figure 2 Important FM parameters



Introduction to frequency-modulated clocks

2.2 TriCore[™] AURIX[™] TC2xx SYSPLL Frequency Modulation

2.2.1 General clocking scheme

AURIX[™] microcontrollers offer several clock domains. Of those domains, SYSPLL can be modulated:

Table 2Available clock domains

Domain	Domain PLL Modulation		Master clocks	Purpose
System clock	SYSPLL	available	SRI, SPB	Operate CPU and peripherals
FlexRay clock	ERAYPLL	not available	ERAY	Operate jitter-critical peripherals
HSSL	HSCTPLL	not available	HSCT	Operate high-speed communication tunnel
AGBT	AGBTPLL	not available	AGBT	Operate gigabit communication channel
Backup clock	n/a	not available	BACKUP	Boot and fall-back clock in case of clock failure

Peripheral functions which may have trouble meeting timing specifications when operated with a modulated clock, are either hard-connected to an unmodulated clock (as listed above), or their clock source can be selected among modulated and unmodulated clock sources.

Note: For further details please refer to the AURIX[™] User Manual.

Table 3 Available clock sources for peripherals

Module	Modulated clock source	Unmodulated clock source
ERAY	no	yes
HSSL	no	yes
AGBT	no	yes
MultiCAN+	yes	yes
ASCLIN	yes	yes
QSPI	yes	yes
I2C	yes	yes
PSI5(S)	yes	yes
MSC	yes	yes
DSADC	yes	yes
VADC	yes	yes
GTM	yes	yes
STM	yes	yes

Note: All other peripherals are operated with the modulated clock whenever modulation is enabled.



Introduction to frequency-modulated clocks

2.2.2 Modulation parameters

2.2.2.1 Modulation scheme and modulation period

AURIX™ microcontrollers use a random Frequency Modulation scheme for the SYSPLL.

The modulation sequence consists of 215-1 = 32767 pseudo-random values.

It uses the crystal oscillator clock divided by P as a reference clock.

After every reference clock period T_{REF} , the SYSPLL VCO is modulated with the next pseudo-random value. $T_{REF} = P / f_{OSC}$ (Equation 2)

Taking as an example a Crystal oscillator clock $f_{OSC} = 20$ MHz and P = 2.

The resulting reference clock period is $T_{REF} = P / f_{OSC} = 100 \text{ ns.}$

The complete "modulation period", consisting of 32767 reference clock periods, takes 3.2767 ms.

Higher crystal frequency or a smaller P divider value reduces the modulation period accordingly. These are the only ways to change the modulation period.

Note: The length of this modulation period is not important. Because of the random type of modulation, the accumulated jitter value saturates a long time before one complete modulation period is over. It has been verified by measurement that the long-term accumulated jitter value is reached after approximately 300 ns.

2.2.2.2 Modulation Amplitude

AURIX[™] microcontrollers accept a maximum MA of 2.0% for the SYSPLL. This value results in a +/- 2% frequency deviation of the system clock around its nominal value, given by:

$$f_{PLL} = f_{OSC} / P \cdot N / K2$$

(Equation 3)

This maximum MA should never be exceeded.

The main reason to use Frequency Modulation is for the related EME reduction. Higher MA causes less EME. On the other hand, the accumulated jitter rises with higher MA. However, the modulation scheme determines the resulting accumulated jitter. For instance, triangular modulation causes high accumulated jitter, as can be calculated using Equation 1. The long-term mean frequency is not influenced by the Frequency Modulation.

The SYSPLL in AURIX[™] microcontrollers implements a "Random Frequency Modulation". It provides significantly less accumulated jitter values than known from triangular modulation schemes.

Due to an intrinsic design-related temperature drift of the MA, the physical real Modulation Amplitude MA_{REAL} deviates from the nominal Modulation Amplitude MA_{NOM} which is programmed by the user.

 MA_{REAL} varies with the fabrication window, supply voltage and temperature ("PVT variation"). Over the whole fabrication window and operating temperature range, the real Modulation Amplitude MA_{REAL} varies around the programmed nominal MA_{NOM} , according to Equations 4 and 5.

The lowest value is (at junction temperature $T_i = 170$ °C):

$MA_{REAL_{MIN}} = 0.5 \cdot MA_{NOM}$
--

The highest value is (at junction temperature $T_j = -40$ °C):

 $MA_{REAL_MAX} = 1.33 \cdot MA_{NOM}$

The programmed MA_{NOM} value should consider:

- 1. Avoid the real modulation amplitude to exceed the maximal allowed value of 2.0% (Condition 1)
- 2. Avoid the long-term accumated jitter to exceed the specified value of 11.5 ns (Condition 2)

Condition 1 is met by any chosen value of MA_{NOM} up to 1.5%, considering the drift numbers given by Equations 4 and 5.

Condition 2 is met by any chosen value of MA_{NOM} up to 1.0%, considering the diagram in Figure 9. Lower MA_{NOM} values increase the EME, and a higher MA_{NOM} values increase the accumulated jitter.

(Equation 4)

(Equation 5)



3 Configuration of the SYSPLL Frequency Modulation

3.1 Summary of recommended system clock Frequency Modulation setting

The recommendation is to operate the SYSPLL with the following parameters:

- f_{OSC} = 20 MHz
- P = 2
- N = 60
- K2 = 3 (for CPU clock 200 MHz) or K2 = 2 (for CPU clock 300 MHz)
- MA_{NOM} = 1.0%

Other configurations are of course possible. However, the programmed nominal Modulation Amplitude MA_{NOM} should not exceed 1.0% in order to stay below the specified maximal long-term accumulated jitter of 11.5 ns under all PVT conditions.

3.2 Recommended register settings for SYSPLL initialization

Prior to clock Frequency Modulation configuration, the SYSPLL must be initialized in order to provide the desired mean system frequency f_{PLL} .

Four parameters determine the system frequency:

- f_{OSC} = Crystal frequency (determined by crystal)
- P = P-divider (configured in register PLLCON0)
- N = N-divider (configured in register PLLCON0)
- Kx-dividers (for different domains); not used for Frequency Modulation (configured in register PLLCON1)

One parameter defines the status of system clock modulation:

- MODEN = modulation enabled/disabled (configured in register PLLCON0)
 One parameter determines the system clock's Modulation Amplitude:
- MODCFG = Modulation Amplitude (configured in register PLLCON2)

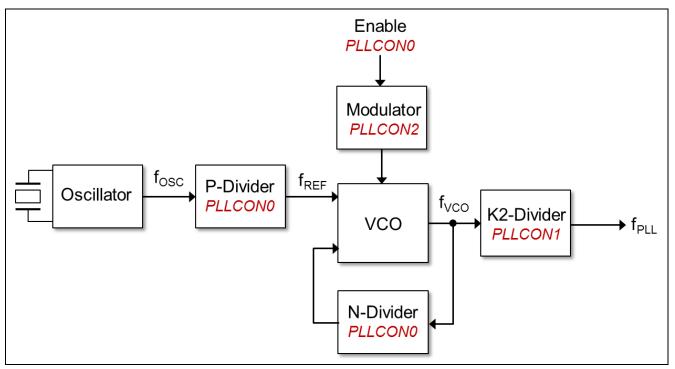


Figure 3 SYSPLL block diagram



3.2.1 PLLCON0 settings for SYSPLL

PLL	Confi	gura	tion 0 I	Reg	ster		(01	8 _H)			Rese	et Va	lue: 0	001 0	600 _H
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
)			PE	viv				0		8	RES LD	0	PLL PWD
		r			r	W				r			W	r	rw
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
			NDIV				0	0	OSC DISC DIS	and the second second	SET FIN DIS	0	MOD EN	VCO PWD	
			rw				rw	r	rw	W	W	rw	rw	rw	rw
ield			Bits	Т	уре	Des	cript	ion							
DIV			[27:24	•] rv	V		ivide value			der o	perate	es is	PDIV-	+1.	
NDIV	<u>.</u>		[15:9]	n	V	The value the P-Divider operates is PDIV+1. N-Divider Value The value the N-Divider operates is NDIV+1.									
NDIV [15:9] rw N-Divider Value The value the N-Divider operates is NDIV+1. MODEN 2 rw Modulation Enable															

m	odulation of the PLL.
0 _E	Frequency modulation is not activated
1 _E	Frequency modulation is activated

Figure 4 SYSPLL-relevant register PLLCON0

The Frequency Modulation is controlled completely digitally and is therefore reliable in respect to the mean frequency deviation, the Modulation Amplitude, and the accumulated jitter.

The Frequency Modulation is turned off after reset and must be explicitly enabled by setting the bit PLLCON0.MODEN.

Before doing so, the SYSPLL has to be initialized in order to provide the desired mean system frequency f_{PLL} and the desired Modulation Amplitude.

Recommended settings

PDIV = $0001\underline{b}$ (→ P = 2) NDIV = $0111011\underline{b}$ (→ N = 60) MODEN =1 (→ enable SYSPLL clock modulation)



3.2.2 PLLCON1 settings for SYSPLL

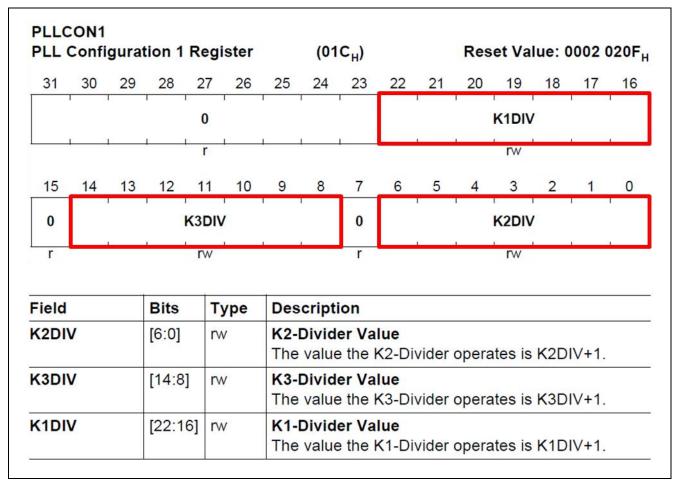


Figure 5 SYSPLL-relevant register PLLCON1

Recommended settings

$$\begin{split} & \text{K2DIV} = 0010\underline{b} \ (\rightarrow \text{K2} = 3 \text{ for } f_{\text{PLL}} = 200 \text{ MHz}) \\ & \text{K2DIV} = 0001\underline{b} \ (\rightarrow \text{K2} = 2 \text{ for } f_{\text{PLL}} = 300 \text{ MHz}) \\ & \text{K1DIV} \text{ and } \text{K3DIV} \text{ according to user system requirements} \end{split}$$



3.2.3 PLLCON2 settings for SYSPLL

The modulation parameters need to be programmed in the register PLLCON2. PLLCON2 contains the bit pattern RGAIN for the MA in the 10-bit field MODCFG[9:0].

LL	Confi	gurat	tion 2	Reg	ister		(020 _H)					Reset Value: 0000 0000 _H					
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16		
								ט ט									
		L	I		1	1	r	w		I		I		I			
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0		
1	1	1	1	0	1		MOD	CFG									
						-	r	W		1				1			
Field			Bits		уре	Des	r								1		

Figure 6 SYSPLL clock Frequency Modulation relevant register PLLCON2

For any desired Modulation Amplitude MA_{NOM} , the corresponding bit-field MODCFG[9:0] can be calculated considering oscillator frequency f_{OSC} , P-divider P and N-divider N, according to Equation 6:

MODCFG[9:0] = RGAIN = HEX (64 • MA_{NOM}/100 • f_{osc}/P • N/3.6); units: MA [%], f_{osc} [MHz] (Equation 6)

Example for recommended Modulation Amplitude MA = 1.0%:

Let fOSC = 20 MHz; P = 2; N = 60 \rightarrow MODCFG[9:0] = 0001101010<u>b</u> = 06A<u>h</u>

The programmed nominal Modulation Amplitude can also be calculated from the bit-field value MODCFG[9:0] as follows:

 $MA_{NOM} = 5.625 \cdot DEC(MODCFG[9:0]) \cdot P / (f_{OSC} \cdot N)$

(Equation 7)



3.2.4 Activating system clock Frequency Modulation

After having completed all other SYSPLL configurations, the system clock Frequency Modulation is activated by setting the MODEN bit (= bit 2) in register PLLCON0.

Whether Frequency Modulation is active or not is indicated by the status bit MODRUN in the register PLLSTAT:

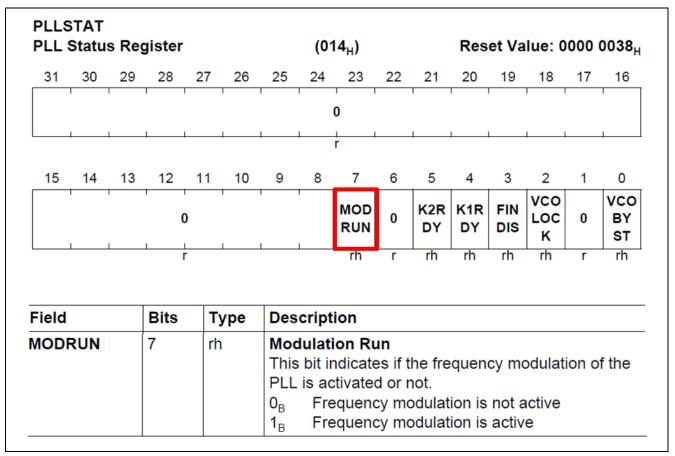


Figure 7 SYSPLL clock Frequency Modulation relevant register PLLSTAT



3.3 Parameter table for other SYSPLL parameters

A nominal Modulation Amplitude $MA_{NOM} = 1.0\%$ is recommended.

Programmed MA_{NOM} values greater than 1.0% may lead to long-term accumulated jitter values J_{ACC} > 11.5 ns, and are therefore not recommended because of specified long-term accumulated jitter limits.

The following table lists the RGAIN values to be programmed into PLLCON2.MODCFG[9:0], depending on the required nominal Modulation Amplitude MA_{NOM} . Note that the SYSPLL VCO is running at 600 MHz in all listed cases. This is the recommended SYSPLL VCO frequency. MA_{NOM} values for other SYSPLL VCO frequencies can be calculated using Equation 6.

Table 4	RGAIN settings as a funct	ion of the programmed Mod	Iulation Amplitude MA _{NOM}
---------	---------------------------	---------------------------	--------------------------------------

f _{OSC} [MHz] =	20	20	20	20	20	20	20	20	20	20	20	20
P =	1	2	1	2	1	2	1	2	1	2	1	2
N =	30	60	30	60	30	60	30	60	30	60	30	60
MA _{NOM} [%] =	0,25	0,25	0,50	0,50	0,75	0,75	1,00	1,00	1,25	1,25	1,50	1,50
RGAIN =	01A	01A	035	035	050	050	06A	06A	085	085	0A0	0A0

Recommended setting!

3.4 Modulation-related effects

3.4.1 Introduction to modulation-related terms

Several physical effects are a function of the programmed (nominal) Modulation Amplitude MA_{NOM} . General values are listed here, with more detail provided in subsequent chapters. Table 5 lists the meaning of frequently used terms in this chapter.

Table 5	Terms used for the explanation of modulation-related effects
---------	--

Term	Abbreviation	Description		
Long-term accumulated jitter J _{ACC}		Saturation value of the accumulated jitter which is reached after a certain time interval		
Short-term accumulated jitter	-	Accumulated jitter value reached after any time interval whic is shorter than that to reach the long-term accumulated jitter		
Time interval error TIE		Equivalent to the short-term or long-term accumulated jitter, depending on the observed time interval. This term is especially related to a time window which is determined by a data transmission protocol. The time window may be the duration of one or more bits in the transmission data stream.		
Maximal time interval error	MTIE	The maximal reached time interval error, equivalent to the long-term accumulated jitter. Any longer observed time window will not show a higher TIE value.		
Data rate	-	The maximal frequency of the data stream. From logical point of view, the data rate may differ wrt. single or double data rate scheme and additional load from frame information, checksum etc. In the context of this application note, "data rate" is meant to be equivalent to a clock signal of a given frequency.		



The SYSPLL in the Infineon AURIX[™] microcontrollers was designed to provide an emission reduction similar to a triangular modulation, while at the same time limiting the accumulated jitter.

The following are the target values of the SYSPLL clock Frequency Modulation, using the recommended value $MA_{NOM} = 1.0\%$. The values have been verified by measurements over full PVT variation.

The system clock f_{PLL} generated by the SYSPLL is spread around its nominal center value:

- $f_{PLLmin} = (1-MA_{REAL}) \cdot f_{OSC} / P \cdot N / K2$; $0.5 \cdot MA_{NOM} < MA_{REAL} < 1.33 \cdot MA_{NOM}$ (Equation 8)
- $f_{PLLmax} = (1+MA_{REAL}) \cdot f_{OSC} / P \cdot N / K2$; $0.5 \cdot MA_{NOM} < MA_{REAL} < 1.33 \cdot MA_{NOM}$ (Equation 9)
- All other clocks derived from the SYSPLL are spread accordingly.

Long-term accumulated jitter $J_{ACC} \le 11.5$ ns. It is valid for time intervals greater than approximately 1 µs – equivalent to a data rate of 1 MHz, after which a "saturation" condition is met.

For fast data communication (i.e. data rates higher than approximately 200 kHz), the short-term accumulated jitter needs to be considered. It is equivalent to the Maximum Time Interval Error MTIE and smaller than the long-term accumulated jitter:

- MTIE < 1.5 ns @ Data rates faster than 25 MHz
- MTIE < 3 ns @ Data rates faster than 10 MHz
- MTIE < 5 ns @ Data rates faster than 5 MHz
- MTIE < 8 ns @ Data rates faster than 3 MHz
- MTIE < 9.5 ns @ Data rates faster than 1 MHz

The mean system clock accuracy is < 0.001%.

The emission reduction compared to unmodulated SYSPLL operation is:

- 3 dB @ peripheral clock (typically f_{PLL}/2 or f_{PLL}//3)
- 9 dB @ CPU clock (typically f_{PLL})
- 15 dB @ higher harmonics of CPU and peripheral clocks

3.4.2 Introduction to accumulated jitter

According to Equations 4 and 5, the real Modulation Amplitude MA_{REAL} has:

minimum value at high temperature $MA_{REAL_{MIN}} = 0.5 \cdot MA_{NOM}$ (at Tj = 180 °C)

maximum value at low temperature $MA_{REAL MAX} = 1.33 \cdot MA_{NOM}$ (at Tj = -50 °C)

Less accumulated jitter at high temperature would cause higher emission, but this effect is partly compensated by reduced transistor switching speed at high temperature, which leads to lower emission.

Summarized, the deviation of the real Modulation Amplitude over temperature does not have significant influence on Electromagnetic Emission. However, care must be taken that the deviation of the accumulated jitter is acceptable by all timing-related microcontroller functions such as data transmission and timer.

In this context it is important to distinguish between long-term and short-term accumulated jitter. The long-term accumulated jitter is the saturation value of clock edge shift caused by the clock modulation. It is reached after approximately 5 µs.



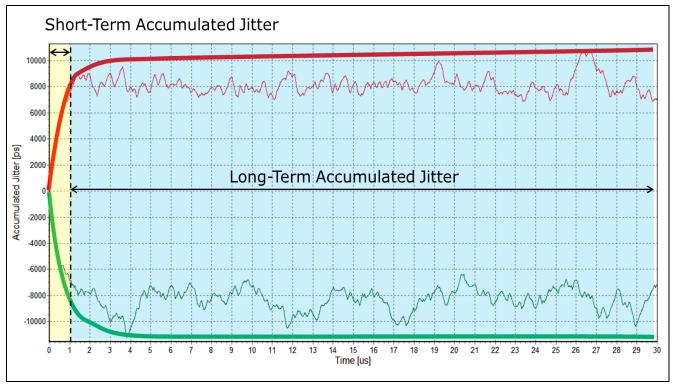


Figure 8 Short-term and long-term accumulated jitter ranges of a measured example

All timings longer than 1 μ s – equivalent to data rates higher than 1 MHz – should be assessed using the longterm accumulated jitter value. Shorter timings should be assessed using the short-term accumulated jitter. Both jitter parameters have been evaluated along with different Modulation Amplitudes. The results are described in subsequent chapters.

The evaluation measurements have been performed over the full PVT variation of the microcontrollers (P = process variation; i.e. fabrication window; V = supply voltages; T = operating temperature). Therefore the results shown within this document can be treated as worst-case values.

3.4.3 Long-term accumulated jitter

The accumulated jitter J_{ACC} rises with MA_{NOM} . It is important to distinguish between the long-term J_{ACC} and the short-term J_{ACC} . The short-term J_{ACC} is related to the Maximum Time Interval Error MTIE, which describes the maximum drift of clock edges after one or more unsynchronized bits of a data transmission. This MTIE is identical to the short-term J_{ACC} for the same time.

The long-term accumulated jitter is the maximum value of the accumulated jitter for all time intervals; i.e. over a time interval of arbitrary length. It depends on the programmed Modulation Amplitude MA_{NOM} and the PVT operating conditions. The worst-case, long-term accumulated jitter stays below 11.5 ns for the *recommended setting* of the nominal Modulation Amplitude $MA_{NOM} \le 1.0\%$ and any PVT variation within the specified operating ranges, see Figure 9. Any $MA_{NOM} \le 1.0\%$ results in an even lower long-term accumulated jitter. Figure 10 shows similar information for MA = 1.5\% for comparison, resulting in max. 15.5 ns long-term accumulated jitter.



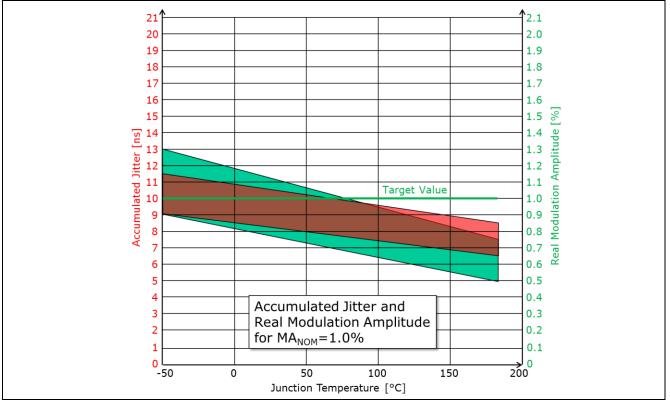


Figure 9 MA_{REAL} and long-term J_{ACC} trends for full PVT variation using recommended $MA_{NOM} = 1.0\%$

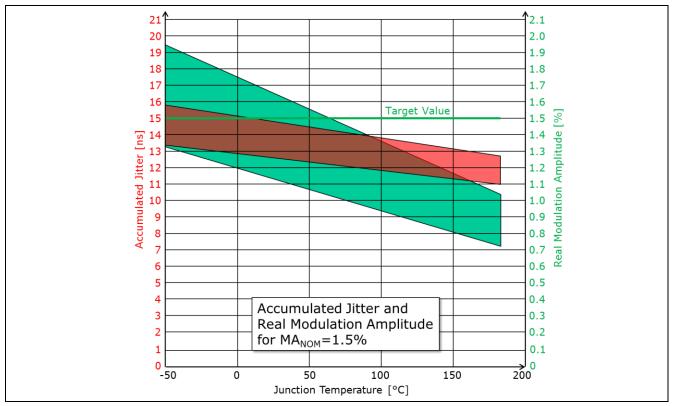


Figure 10 MA_{REAL} and long-term J_{ACC} trends for full PVT variation using $MA_{NOM} = 1.5\%$



MA _{NOM}	Measured J _{ACC}	J _{ACC} spec. 21 ns	J _{ACC} spec. 15.5 ns	J _{ACC} spec. 11.5 ns	J _{ACC} spec. 9 ns	J _{ACC} spec. 6 ns
0.5 %	<6 ns	ок	ОК	OK	ОК	ок
0.8 %	<9 ns	OK	OK	ОК	OK	FAIL
1.0 %	<11.5 ns	OK	OK	ОК	FAIL	FAIL
1.5 %	<16 ns	ОК	OK	FAIL	FAIL	FAIL
2.0 %	<21 ns	ОК	FAIL	FAIL	FAIL	FAIL

Table 6 Long-term accumulated jitter (J_{ACC}) spec violation as function of MA overfull PVT variation

The following diagram shows the long-term accumulated jitter trend, depending on the selected nominal Modulation Amplitude MA_{NOM} and the SYSPLL divider settings P and N. In all cases, the oscillator frequency is 20 MHz and the SYSPLL VCO frequency is 600 MHz.

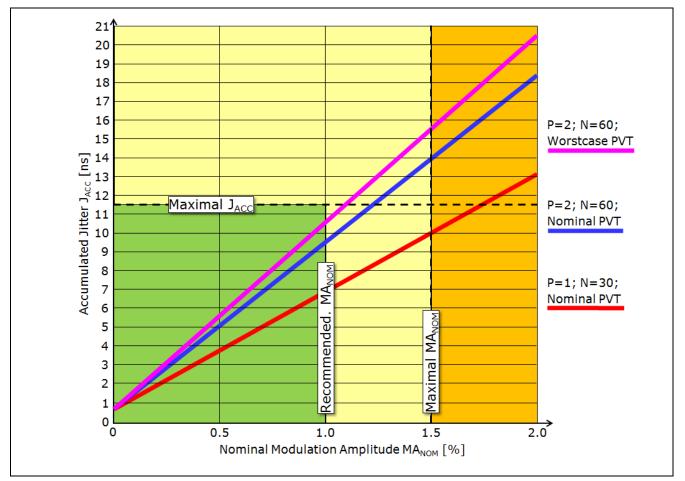


Figure 11 Long-term J_{ACC} trends as function of MA_{NOM} and SYSPLL dividers

The blue and red lines indicate the jitter values for a nominal device (centered fabrication window) operated under nominal conditions (room temperature, nominal supply voltages).

The jitter value deviation for different P and N divider settings is clearly visible. The random frequency modulator takes the crystal oscillator clock divided by P as a reference clock.

With every reference clock period the VCO of the SYSPLL is modulated by a new value. It is apparent therefore, that a smaller P value leads to less accumulated jitter. On the other hand, emission increases accordingly.

Since the motivation for PLL clock spreading is reaching lowest emission, we recommend to use the divider values P = 2 and N = 60 for the modulated SYSPLL.



The magenta line indicates the maximum jitter values occurring over full PVT (fabrication window, specified operating supply voltage range, specified operating temperature range) variation. The J_{ACC} values in Table 6 are taken from this limit line.

3.4.4 Short-term accumulated jitter and time interval error

For short time intervals in the range between zero and approximately 300 ns, the accumulated jitter is considerably smaller than the long-term jitter value. This is especially important when the Maximum Time Interval Error (MTIE) for data protocols is considered.

The MTIE describes the edge shift between an ideally constant clock and a jittered or modulated clock. It is equivalent to the short-term accumulated jitter. Considering the MTIE is essential to assess the protocol timings of asynchronous data interfaces or other time-critical functions.

According to the following two diagrams, the short-term accumulated jitter covers time intervals shorter than 500 ns, which is equivalent to data rates faster than 2 MHz.

Note: Data protocols may specify data frames. The communication channel is re-synchronized after one frame.

Example calculation

The data rate is assumed to be 50 MHz; i.e. one bit lasts for 20 ns.

One data frame accumulates 10 data bits.

10 · 20 ns = 200 ns.

This interval is equivalent to a data rate of 5 MHz.

In the diagram below, for 1.0% nominal Modulation Amplitude (blue line), an MTIE of 5 ns is assigned to a 5 MHz data rate. This is less than half of the maximal long-term accumulated jitter (11.5 ns) for 1.0% nominal Modulation Amplitude. This judgement of the individual MTIE values for the data interfaces is recommended in order to determine which highest Modulation Amplitude can be accepted for the correct operation of all data interfaces.

Long-term accumulated jitter values apply to low-speed data rates below ca. 1 MHz. For these data rates, the MTIE is approximately equal to the long-term accumulated jitter for the selected Modulation Amplitude.

Figure 12 illustrates the MTIE trend for data rates from 10 kHz to 100 MHz, depending on the selected nominal Modulation Amplitude MA_{NOM} . The SYSPLL divider settings are: $f_{OSC} = 20$ MHz, P = 2, N = 60, K2 = 3. For faster data rates, the MTIE becomes significantly lower than the long-term accumulated jitter.



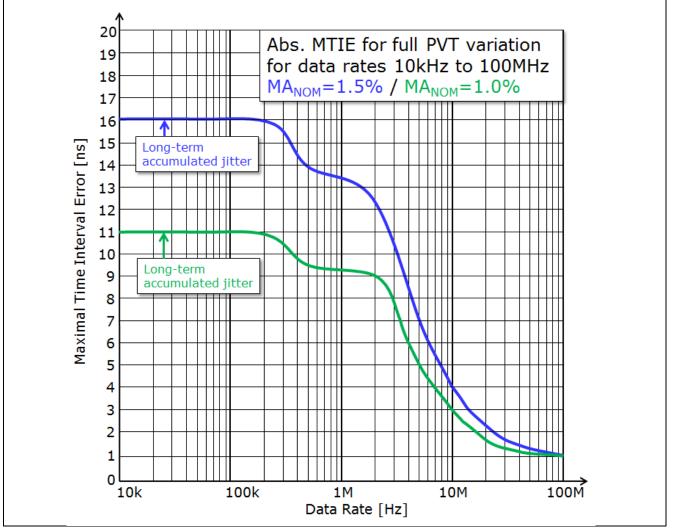


Figure 12 Absolute values for short-term accumulated jitter = Maximum Time Interval Error (MTIE)

Protocols using slow data rates accept typically a higher absolute MTIE value. Therefore it makes sense to introduce the "Relative MTIE" which is the ratio between the "Absolute MTIE" at this data rate and the duration of one bit at this data rate. Although the absolute MTIE values increase with slower data rates, the relative MTIE becomes smaller with slower data rates, indicating that a dedicated MTIE value is less critical for low-speed data communication. For the example above, the 7 ns short-term jitter is equivalent to 3.5 % of the 200 ns time interval.

Figure 13Figure 12 illustrates the trend of the MTIE to data bit length ratio for data rates from 10 kHz to 100 MHz, depending on the selected nominal Modulation Amplitude MA_{NOM} . The SYSPLL divider settings are: $f_{OSC} = 20$ MHz, P = 2, N = 60, K2 = 3. For slower data rates, this ratio gets significantly low, indicating that slow data transfers should not violate the underlying protocol. High data rates imply a higher ratio and should be investigated carefully.



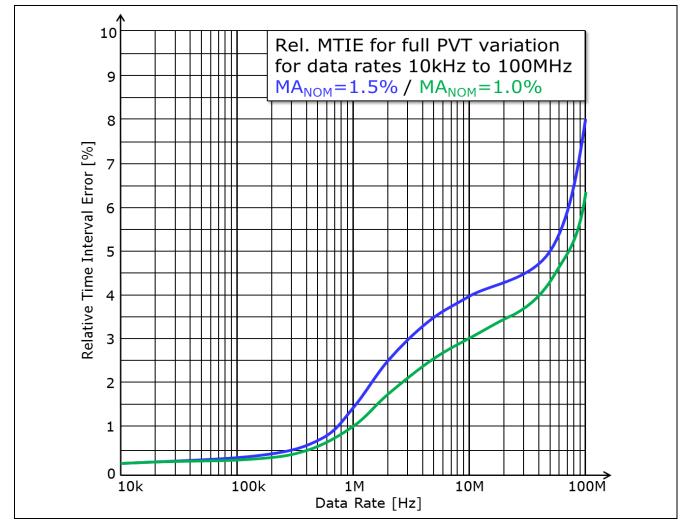


Figure 13 Ratio values for Maximum Time Interval Error (MTIE) divided by data bit length



3.4.4.1 MTIE values for different data rates

A variety of data rates along with their absolute MTIE values and MTIE to bit length ratio numbers are listed in Table 7 for different MA_{NOM} values between 1.0% and 2.0%.

Table 7 Maximum Time Interval Error for different data rates and Modulation Amplitudes

		MA _{NOM} =1,0%	MA _{NOM} =1,0%	MA _{NOM} =1,5%	MA _{NOM} =1,5%	MA _{NOM} =2,0%	MA _{NOM} =2,0%
Data-Rate [MHz]	Bit-Length [ns]	Max-MTIE [ns]	MTIE/Bit-Length [%]	Max-MTIE [ns]	MTIE/Bit-Length [%]	Max-MTIE [ns]	MTIE/Bit-Length [%]
100	10	0,606	6,06%	0,761	7,61%	0,825	8,25%
50	20	0,868	4,34%	0,981	4,91%	1,025	5,13%
33,33	30	0,979	3,26%	1,294	4,31%	1,794	5,98%
25	40	1,046	2,62%	1,83	4,58%	2,005	5,01%
20	50	1,517	3,03%	1,993	3,99%	2,756	5,51%
16,67	60	1,844	3,07%	2,456	4,09%	2,979	4,97%
12,5	80	2,011	2,51%	3,001	3,75%	3,948	4,94%
10	100	2,768	2,77%	3,846	3,85%	4,926	4,93%
6,67	150	3,846	2,56%	5,137	3,42%	6,866	4,58%
5	200	4,882	2,44%	6,894	3,45%	8,652	4,33%
4	250	5,831	2,33%	8,212	3,28%	10,417	4,17%
3,33	300	6,627	2,21%	9,244	3,08%	11,96	3,99%
2,5	400	7,923	1,98%	11,525	2,88%	14,989	3,75%
2	500	8,63	1,73%	12,631	2,53%	16,433	3,29%
1,67	600	7,955	1,33%	11,908	1,98%	15,193	2,53%
1,25	800	8,052	1,01%	12,047	1,51%	15,97	2,00%
1	1000	8,311	0,83%	12,136	1,21%	16,761	1,68%
0,67	1500	8,454	0,56%	12,392	0,83%	16,86	1,12%
0,5	2000	8,301	0,42%	12,744	0,64%	16,99	0,85%
0,33	3000	8,87	0,30%	13,407	0,45%	17,443	0,58%
0,25	4000	10,24	0,26%	15,433	0,39%	20,165	0,50%
0,2	5000	7,725	0,15%	11,786	0,24%	15,39	0,31%
0,1	10000	8,729	0,09%	12,772	0,13%	17,005	0,17%



3.4.5 Electromagnetic Emission

Electromagnetic Emission (EME) is measured under nominal PVT conditions; i.e. centered fabrication lot, nominal supply voltages and room temperature. These conditions lead to approximately 80°C junction temperature for typical microcontroller operation, and the real Modulation Amplitude MA_{REAL} is ca. 20% lower than the programmed Modulation Amplitude MA_{NOM} .

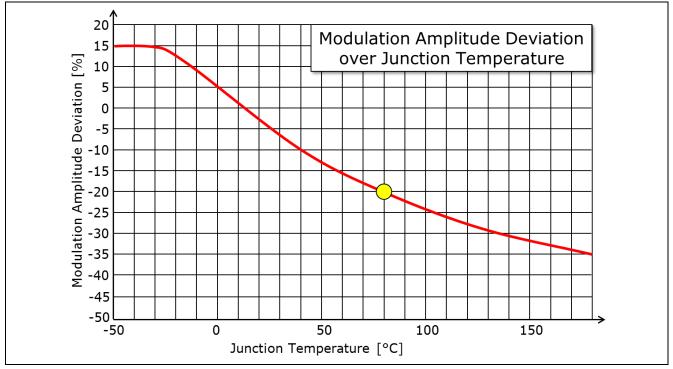


Figure 14 Deviation of MA over junction temperature for a POR device supplied by nominal voltages

EME decreases with higher temperature because CMOS transistors become slower. This trend is partially compensated by the reduced MA towards high temperature. Therefore the EME is expected to stay approximately stable over temperature.

The lowest emission (especially at low-order system clock harmonics) is reached for SYSPLL divider settings P = 2, N = 60, K2 = 3. SYSPLL divider settings P = 1, N = 30, K2 = 3 lead to significantly higher emission.

This trend is the opposite of the accumulated jitter trend. The long-term accumulated jitter is higher for divider settings P = 2, N = 60, K2 = 3.

Considering the fact that most microcontroller timings are related to the short-term accumulated jitter which is significantly smaller than the long-term accumulated jitter, low emission should get priority over small long-term jitter.

Figure 15 shows the EME trend depending on the SYSPLL divider settings P and N. The parameters are: oscillator frequency is 20 MHz; nominal Modulation Amplitude $MA_{NOM} = 1.5\%$.

The similar behaviour can be assumed for $MA_{NOM} = 1.0\%$.

Due to the Modulation Amplitude deviation at nominal PVT conditions (i.e. emission measurement conditions), the following translation between MA_{NOM} and MA_{REAL} is valid:

Table 8 Relationship between nominal and real Modulation Amplitudes

MA _{NOM} [%]	MA _{REAL} [%]		
0.5	0.4		
1.0	0.8		
1.25	1.0		
1.5	1.2		



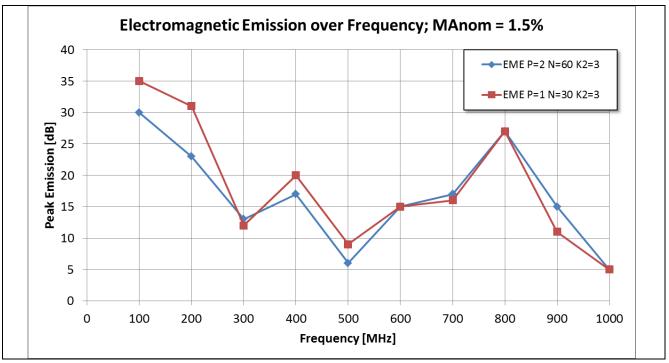


Figure 15 EME trends as function of SYSPLL dividers

For $MA_{NOM} = 1.5\%$ ($MA_{REAL} = 1.2\%$), an emission reduction of up to 20 dB is achieved. Note that emission reduction is less for low-order clock harmonics.

The next diagram shows the level of emission reduction for different real Modulation Amplitudes MAREAL.

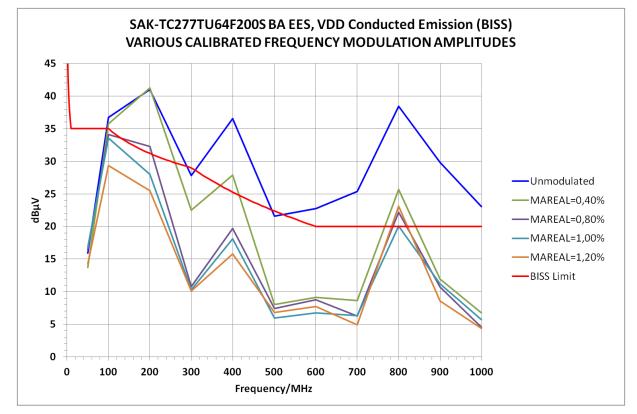


Figure 16 Emission comparison for several real Modulation Amplitudes (MA_{REAL} = 0.8 · MA_{NOM})



The following figures show the measured emission spectra of the AURIXTM microcontroller TC277-BA for disabled SYSPLL Frequency Modulation and several SYSPLL Frequency Modulation Amplitudes $MA_{NOM} = 0.5\%$, 1.0%, 1.25%, and 1.5%, respectively. Due to the Modulation Amplitude deviation at nominal PVT conditions (i.e. emission measurement conditions), the resulting real Modulation Amplitudes ($MA_{REAL} = 0.8 \cdot MA_{NOM}$) are: $MA_{REAL} = 0.4\%$, 0.8%, 1.0%, and 1.2%, respectively, see **Error! Reference source ot found.**

The following table shows the absolute peak emission values for $0.5 \cdot f_{CPUx}$ up to 5 f_{CPUx} as a function of MA.

Harmonic	Frequency [MHz]	Peak emission [dB]						
		FM off MA _{REAL} =0% MA _{NOM} =0%	FM on MA _{REAL} =0.4% MA _{NOM} =0.5%	FM on MA _{REAL} =0.8% MA _{NOM} =1.0%	FM on MA _{REAL} =1.0% MA _{NOM} =1.25%	FM on MA _{REAL} =1.2% MA _{NOM} =1.5%		
0.5 · f _{CPUx}	100	37	36	34	34	29		
f _{CPUx}	200	41	41	32	28	25		
1.5 · f _{CPUx}	300	28	22	11	10	10		
2 · f _{CPUx}	400	37	28	20	18	17		
2.5 · f _{CPUx}	500	22	8	7	6	7		
3 · f _{CPUx}	600	23	9	9	7	8		
3.5 · f _{CPUx}	700	25	8	7	6	6		
4 · f _{CPUx}	800	38	26	22	20	23		
4.5 · f _{CPUx}	900	30	12	11	11	9		
5 · f _{CPUx}	1000	23	7	7	6	5		

Table 9Emission peak values for the clock harmonics from 100 MHz up to 1000 MHz

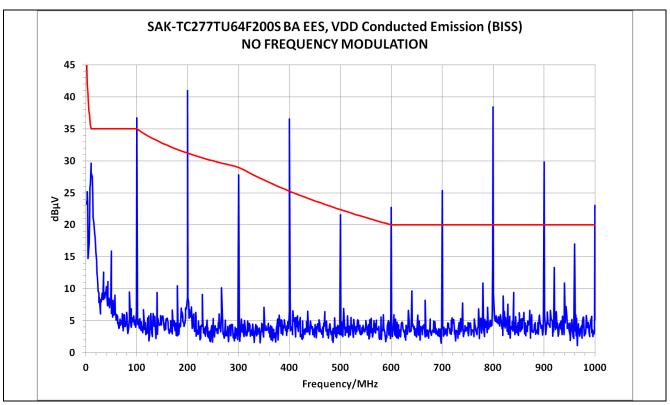


Figure 17 Reference emission without FM





Measured EME reduction with SYSPLL clock Frequency Modulation under nominal PVT conditions

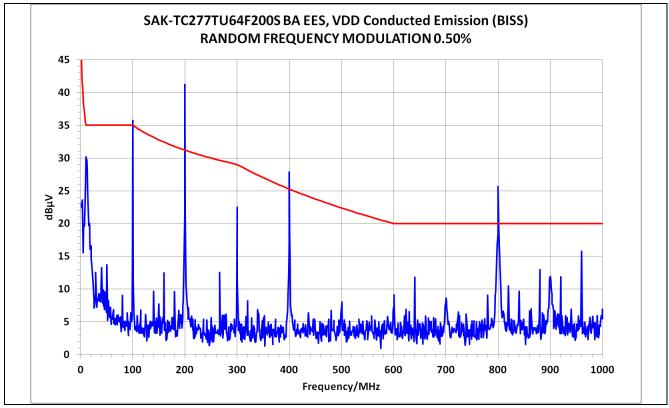


Figure 18 Emission for MA_{NOM}=0.5% (MA_{REAL}=0.4%)

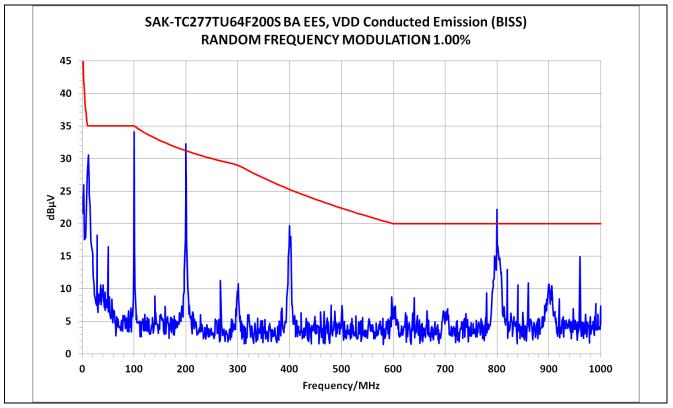


Figure 19 Emission for MA_{NOM}=1.0% (MA_{REAL}=0.8%)



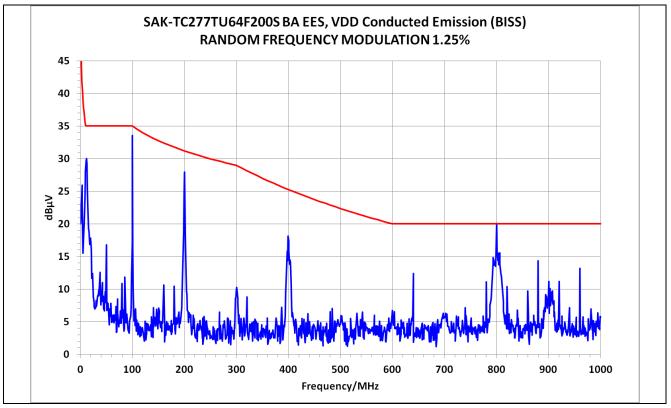


Figure 20 Emission for MA_{NOM}=1.25% (MA_{REAL}=1.0%)

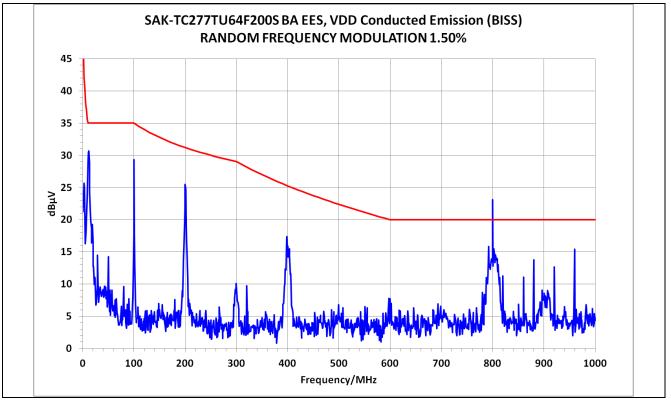


Figure 21 Emission for MA_{NOM}=1.5% (MA_{REAL}=1.2%)



3.4.6 Clock frequency accuracy

Using Frequency Modulation, the long term (> 600 µs) accuracy of the mean system clock frequency stays below:

 $\pm\,0.002\%$ over full PVT variation for MA_{NOM} = 1.5%

 \pm 0.001% over full PVT variation for MA_{NOM} = 1.0%

The diagram below shows the maximum mean frequency deviation over time intervals from 100 ns up to 1 ms over full PVT variation. Note that the short-term mean frequency accuracy is significantly higher for shorter time intervals since the compensation of modulated clock period length needs some time.

0.1% accuracy of the mean frequency when using modulation are reached after 20 μs for MA_{NOM} = 1.5% and after 8 μs for MA_{NOM} = 1.0%.

0.01% accuracy of the mean frequency when using modulation are reached after 200 μs for MA_{NOM} = 1.5% and after 80 μs for MA_{NOM} = 1.0%.

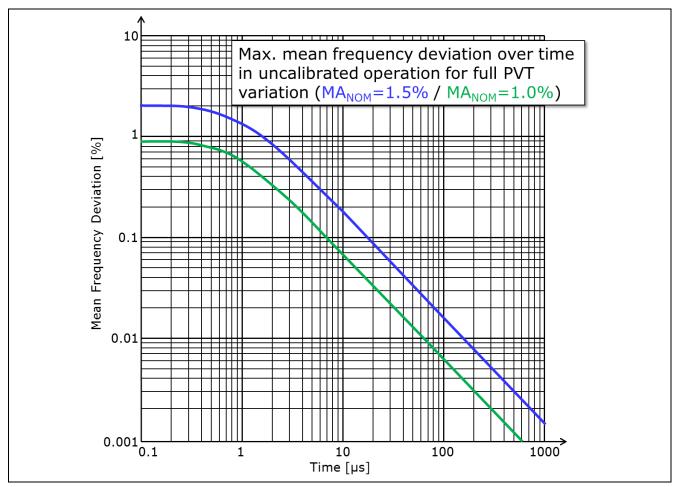


Figure 22 Mean frequency deviation over time for $MA_{NOM} = 1.5\%$ and $MA_{NOM} = 1.0\%$

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